Thin Film Technology | processes & equipment

■ **Package on a pressure capsule**

1µm
300nm
200nm
5µm
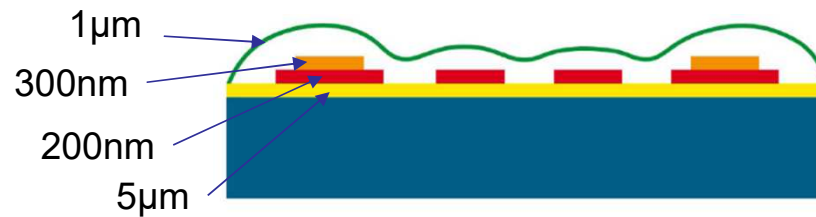
Thin film structures for sensor applications

- Passivation layer
- Contact pads
- Functional layer
- Insulation layer
- Substrate

P

Membran
(substrate)

R_2 R_1 R_3 R_4

$\varepsilon > 0$
$\varepsilon < 0$

(Є = elongation)

R_1 R_4

(ΔU)

R_2 R_3

(U)